

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Sang-Guen Kim, Seung-Chul Ahn
Assignee: Samsung Electronics Co., Ltd.
Title: Die Bonding Equipment (As Amended)
Serial No.: Unknown Filing Date: August 6, 2001
Examiner: Unknown Group Art Unit: Unknown
Docket No.: AB-878-1D US

San Jose, California
August 3, 2001

BOX Patent Application
COMMISSIONER FOR PATENTS
Washington, D. C. 20231

PRELIMINARY AMENDMENT

Dear Sir:

Please enter the following amendments in the above-identified and accompanying Divisional Patent Application, which is a divisional of U.S. Patent Application Serial No. 09/406,916 filed September 24, 2000 ("the Parent Application"), before taking it up for examination.

IN THE TITLE

Please amend the title to read: "DIE BONDING EQUIPMENT".

IN THE CLAIMS

Please cancel Claims 1-11, and 17-20, leaving Claims 12-16 for prosecution in this application.

IN THE SPECIFICATION

Please amend the paragraphs of the specification as indicated in the mark-up of those paragraphs in Attachment A. The following paragraphs are clean versions of the amended paragraphs.

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